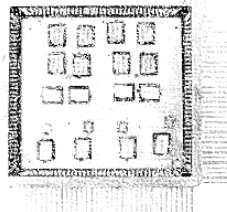


# Product Data Sheet



## Product MCT 5341-25LV2

UV CURABLE NON SILICONE FLEXIBLE GLOB TOP FOR SEMI'S AND MCM'S

### A NEW DEVELOPMENT FOR GLOBTOP AND FINE WIRE PROTECTION FOR RF DEVICES

RoHS Compliant and No Heavy Metals

#### PRODUCT DESCRIPTION

MCT 5341-25LV2 has been specifically developed to rid the workplace of Silicones and eliminate the high power requirements for the UV cure of these materials. Developed for microwave circuitry to over 100Gbs for ultrathin die with multiple wirebonds for either completely covering the die and wirebonds or only coating the base of the package and second bond areas to keep the top of the active die clear of material.

This is a Semiconductor/Microelectronic Grade UV curable glob top that bonds well to a variety of substrates including ceramic, LCP, PCB, Kovar, and polycarbonate. The cured product is very flexible, and is highly resistant to environmental stress and repeated thermal cycling. MCT 5341-25LV2 develops high peel strength and is ideally suited for flexible glob top over die/wirebonds including Multichip Modules. The cured surface of MCT 5341-25LV2 remains slightly tacky.

534125LV-2 has a number of outstanding processing advantages; No mixing is necessary prior to use; NO SILICONES! NO VOC's! This material is **not** "Pre-mixed and Frozen"; The viscosity remains constant with time (i.e. it will not thicken over time); Working life is unlimited at room temperature, and the material is room temperature storable; No cleanup required in-between shifts;

#### UNCURED PROPERTIES

Composition	Aliphatic Urethane Acrylate / Monomer Blend
Viscosity	6100 cps at 25 <sup>0</sup> C.
Appearance	Clear liquid
Specific Gravity	1.07 at 25 <sup>0</sup> C.
Flash Point	>38 <sup>0</sup> C.
Toxicity	Refer to Material Safety Data Sheet

#### CURED PROPERTIES

Durometer Shore A	<10
H2O Absorption	Less than <0.6% (24 hour immersion)
Useful Temp Range	-40 <sup>0</sup> C. to 130 <sup>0</sup> C.
Refractive Index	1.46 at 24 <sup>0</sup> C. (typical, not a specification)
Thermal Breakdown Temp	>300 <sup>0</sup> C.
Thermal Conductivity	0.45 W/mK
Dielectric Strength	9.5 kV/mm
E-Modulus	324 N/mm <sup>2</sup>
Elongation at Break	325%
Tg	<25C
CTE 10 <sup>-6</sup> (cm/cm)/ <sup>0</sup> C	130-200 (Do not use as specification)
Post Cure Ionics 883/5011.3.8.7	Cl=<6ppm, Na+=<3.3ppm, K+=<1.1ppm

#### CURING

<u>UV Intensity</u>	<u>Substrates</u>	<u>Bond Gap</u>	<u>Time to Cure</u>
100 mW/cm <sup>2</sup>	glass-glass	1-2 mils	<10 seconds
Absorption spectrum	300 to 400 nm, with peak at 365.		

Supplied in 3cc, 5cc, 10cc, and 30cc opaque syringes

Shelf Life: One year at 25C from date of shipment

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